

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V _{CBO}	100	V
Collector-Emitter Voltage	V _{CEO}	50	
Emitter-Base Voltage	V _{EBO}	7	
Peak Pulse Current	I _{CM}	6	A
Continuous Collector Current	I _C	4	
		4.3	
Base Current	I _B	1	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

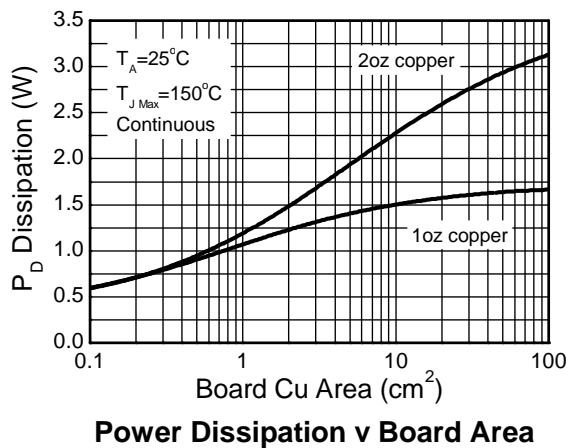
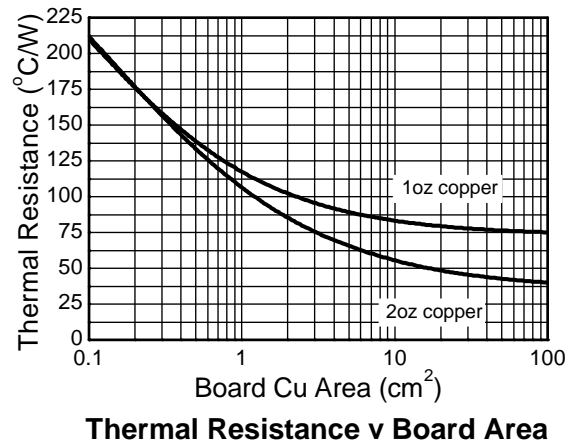
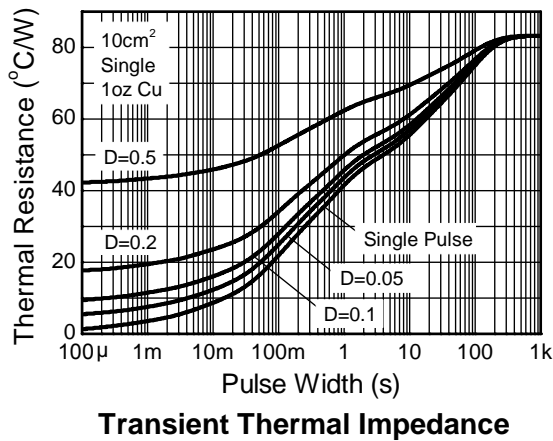
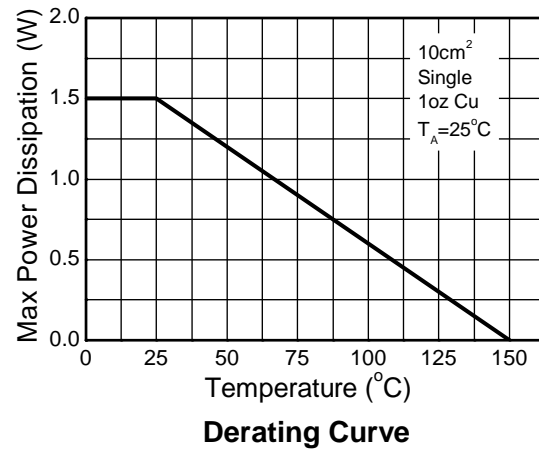
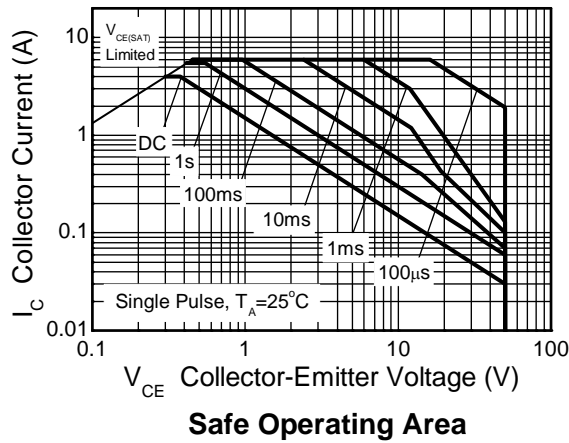
Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	1.5	W
Linear Derating Factor		12	
		2.45	mW/°C
		19.6	
Thermal Resistance, Junction to Ambient	R _{θJA}	83	°C/W
		51	
Thermal Resistance, Junction to Lead	R _{θJL}	16.8	°C
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	

ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted with the exposed collector pad on 31mm x 31mm (10cm²) 1oz copper that is on a single sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state. The entire exposed collector pad is attached to the heatsink.
 6. Same as Note 5, except the device is measured at t ≤ 5s.
 7. Thermal resistance from junction to solder-point (on the exposed collector pad).
 8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

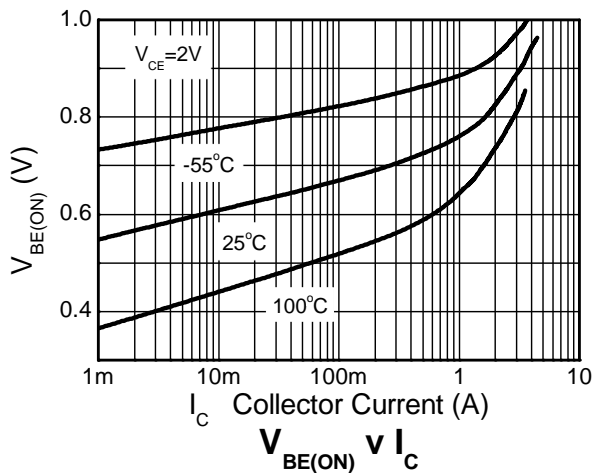
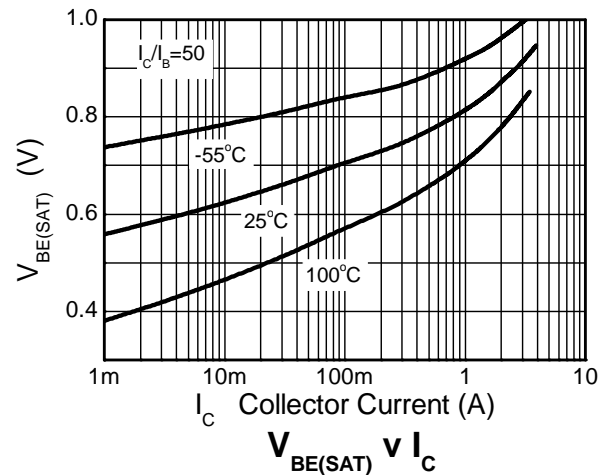
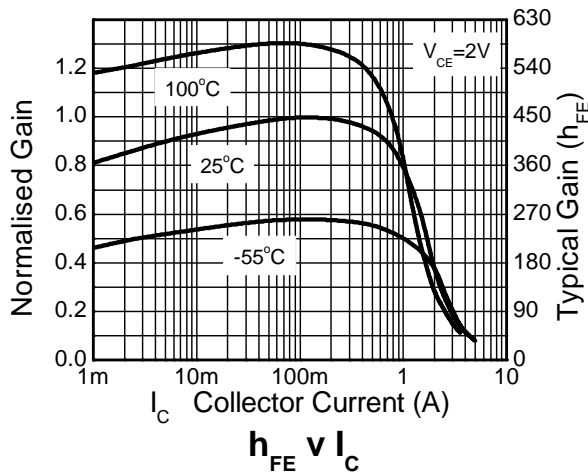
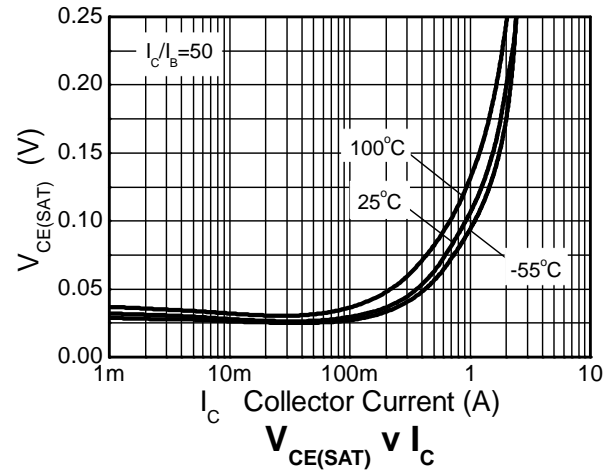
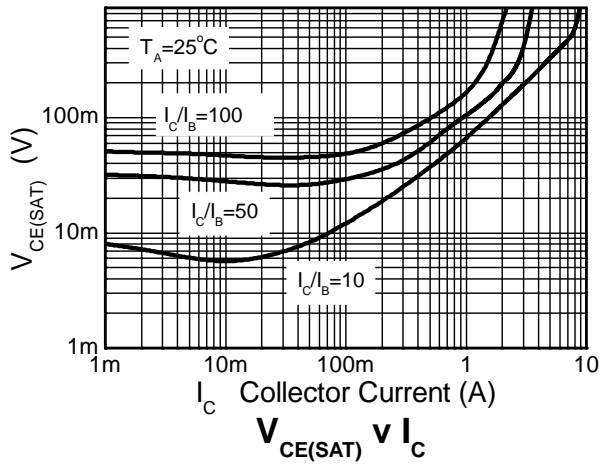


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	100	190	—	V	I _C = 100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	50	65	—	V	I _C = 10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	7	8.2	—	V	I _E = 100μA
Collector Cutoff Current	I _{CBO}	—	—	100	nA	V _{CB} = 80V
Emitter Cutoff Current	I _{EBO}	—	—	20	nA	V _{EB} = 6V
Collector Emitter Cutoff Current	I _{CES}	—	—	100	nA	V _{CES} = 40V
Static Forward Current Transfer Ratio (Note 9)	h _{FE}	200 300 200 100 —	400 450 400 225 40	— — — — —	—	I _C = 10mA, V _{CE} = 2V I _C = 200mA, V _{CE} = 2V I _C = 1A, V _{CE} = 2V I _C = 2A, V _{CE} = 2V I _C = 6A, V _{CE} = 2V
Collector-Emitter Saturation Voltage (Note 9)	V _{CE(SAT)}	— — — — — —	10 70 145 150 225 270	20 100 200 220 300 320	mV	I _C = 0.1A, I _B = 10mA I _C = 1A, I _B = 50mA I _C = 1A, I _B = 10mA I _C = 2A, I _B = 50mA I _C = 3A, I _B = 100mA I _C = 4A, I _B = 200mA
Base-Emitter Turn-On Voltage (Note 9)	V _{BE(ON)}	—	0.94	1.00	V	I _C = 4A, V _{CE} = 2V
Base-Emitter Saturation Voltage (Note 9)	V _{BE(SAT)}	—	1.00	1.07	V	I _C = 4A, I _B = 200mA
Output Capacitance	C _{OBO}	—	12	20	pF	V _{CB} = 10V, f = 1MHz
Transition Frequency	f _T	100	165	—	MHz	V _{CE} = 10V, I _C = 50mA, f = 100MHz
Turn-On Time	t _{ON}	—	170	—	ns	V _{CC} = 10V, I _C = 1A
Turn-Off Time	t _{OFF}	—	750	—	ns	I _{B1} = -I _{B2} = 10mA

Note: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

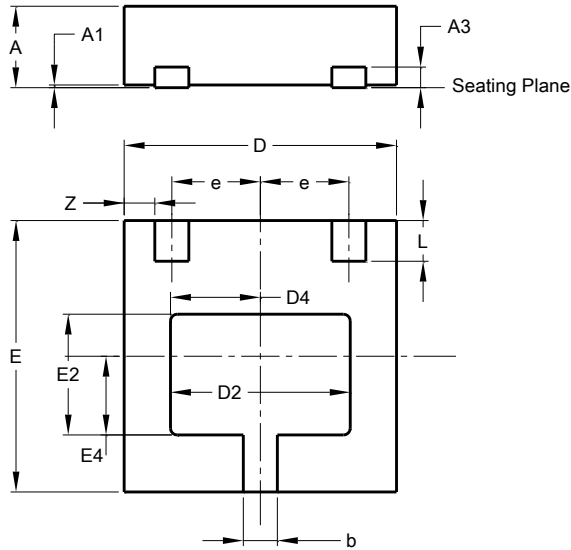
Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-3 (Type B)

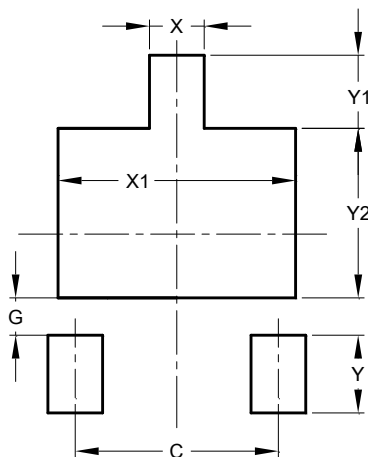


U-DFN2020-3 (Type B)			
Dim	Min	Max	Typ
A	0.57	0.63	0.60
A1	0.00	0.05	0.02
A3	—	—	0.152
b	0.20	0.30	0.25
D	1.950	2.075	2.00
D2	1.22	1.42	1.32
D4	0.56	0.76	0.66
E	1.950	2.075	2.00
E2	0.79	0.99	0.89
E4	0.48	0.68	0.58
e	—	—	0.65
L	0.25	0.35	0.30
Z	—	—	0.225
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-3 (Type B)



Dimensions	Value (in mm)
C	1.300
G	0.240
X	0.350
X1	1.520
Y	0.500
Y1	0.470
Y2	1.090

IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or
2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2019, Diodes Incorporated

www.diodes.com